therein, at least one of said terminal-forming areas including a plurality of terminal parts such that each pair of said terminal parts within any one of said terminal-forming areas is closer to each other than any pair of said terminal parts in different ones of said terminal-forming areas;

forming an anisotropic conductive layer on said target surface so as to span said plurality of terminal-forming areas;

placing said plurality of electronic components on said anisotropic conductive layer individually above said plurality of terminal-forming areas; and

pressing said plurality of electronic components to said anisotropic conductive layer so as to thereby cause said conductive connecting members of said plurality of electronic components to individually become adhered to and in electrically conductive relationship with a corresponding one of said terminal parts through said anisotropic conductive layer.

C1 Concluded

REMARKS

Claims 1, 2, 4, 6 and 7 currently remain in the application. Claims 3, 5, 8 and 9 have been withdrawn as non-elected claims. Claim 1 is amended herein.

Claims 1, 2, 4, 6 and 7 were rejected firstly under 35 U.S.C. 112 as being indefinite. In response, independent claim 1, from which all the other rejected claims depend, has been amended herein to more clearly state (1) that there are a plurality of what are each herein referred to as the "terminal-forming area", (2) that each of these terminal-forming areas includes one or more of what are each herein referred to as the "terminal-forming part", (3) that at least one of these terminal-forming areas includes (not just one but) a plurality of terminal parts, and (4) that on those of the terminal-forming areas including more than one terminal-forming part, these plurality of terminal-forming parts are more closely clustered than between any pair of the terminal-forming parts in different ones of these terminal-forming areas. Thus rewritten, claim 1 is believed to contain no ambiguities as to the number of terminal-forming parts among the terminal-forming areas.

Claims 1, 2, 4, 6 and 7 were rejected secondly under 35 U.S.C. 102 as being anticipated by Matsui. It is well settled, however, that rejection of a claim under 35 U.S.C.

102 is justified only if a single reference discloses every inventive element in that claim. In the instant case, Matsui was cited evidently for disclosing the formation of an isotropic conductive layer. The distribution of terminal-forming parts over terminal-forming areas as described above in amended claim 1 is not disclosed or even hinted at. The amendment effected herein on claim 1 is believed to overcome also the Examiner's rejection on the anticipation ground.

In summary, it is believed that the instant Amendment is completely responsive to the Office Action and hence that the application is now in condition for allowance.

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "Version with markings to show changes made."

Respectfully submitted,

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December 3, 2001
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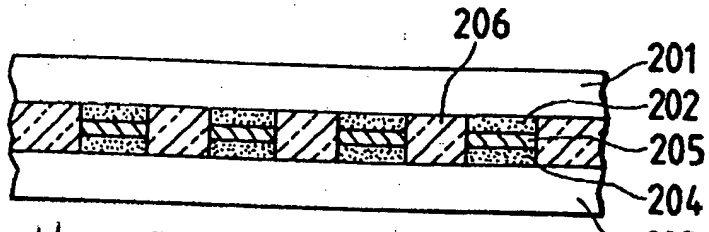
Claim Tree

FIG. 4



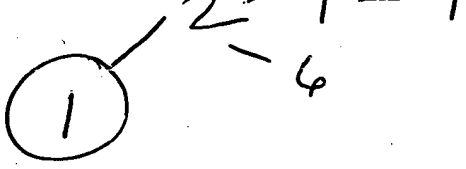


FIG. 5(a)

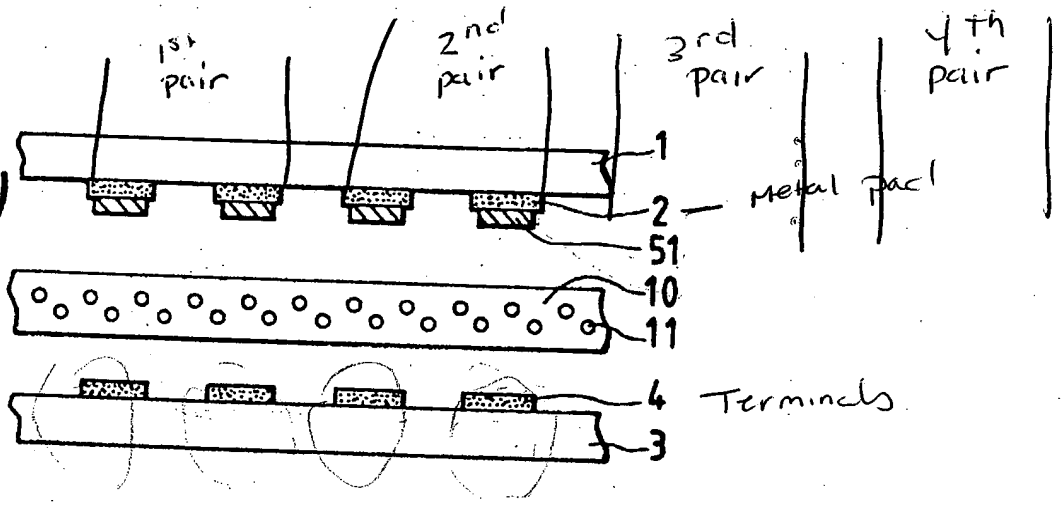
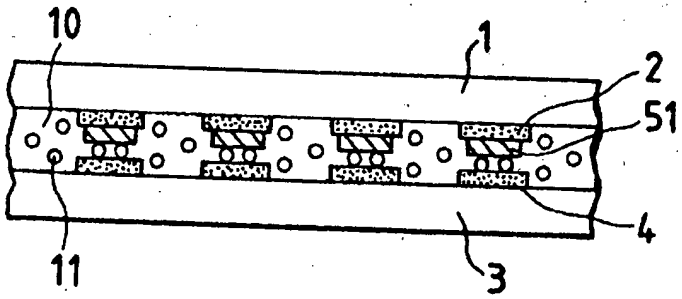


FIG. 5(b)



* The first pair is closer second pair than that of the 3rd pair etc.

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

Claim 1 has been amended as follows:

1. (Thrice amended) A method of surface-mounting a plurality of electronic components having conductive connecting members, said method comprising the steps of:

providing a target surface having a plurality of specified terminal-forming areas thereon, each of said specified terminal-forming areas including ~~one or more terminal parts~~ at least one terminal part therein, ~~said terminal parts being clustered~~ at least one of said terminal-forming areas including a plurality of terminal parts such that ~~those of~~ each pair of said terminal parts within ~~a same~~ any one of said terminal-forming areas ~~are~~ is closer ~~together~~ to each other than ~~those~~ any pair of said terminal parts in different ones of said terminal-forming areas;

forming an anisotropic conductive layer on said target surface so as to span said plurality of terminal-forming areas;

placing said plurality of electronic components on said anisotropic conductive layer individually above said plurality of terminal-forming areas; and

pressing said plurality of electronic components to said anisotropic conductive layer so as to thereby cause said conductive connecting members of said plurality of electronic components to individually become adhered to and in electrically conductive relationship with a corresponding one of said terminal parts through said anisotropic conductive layer.